












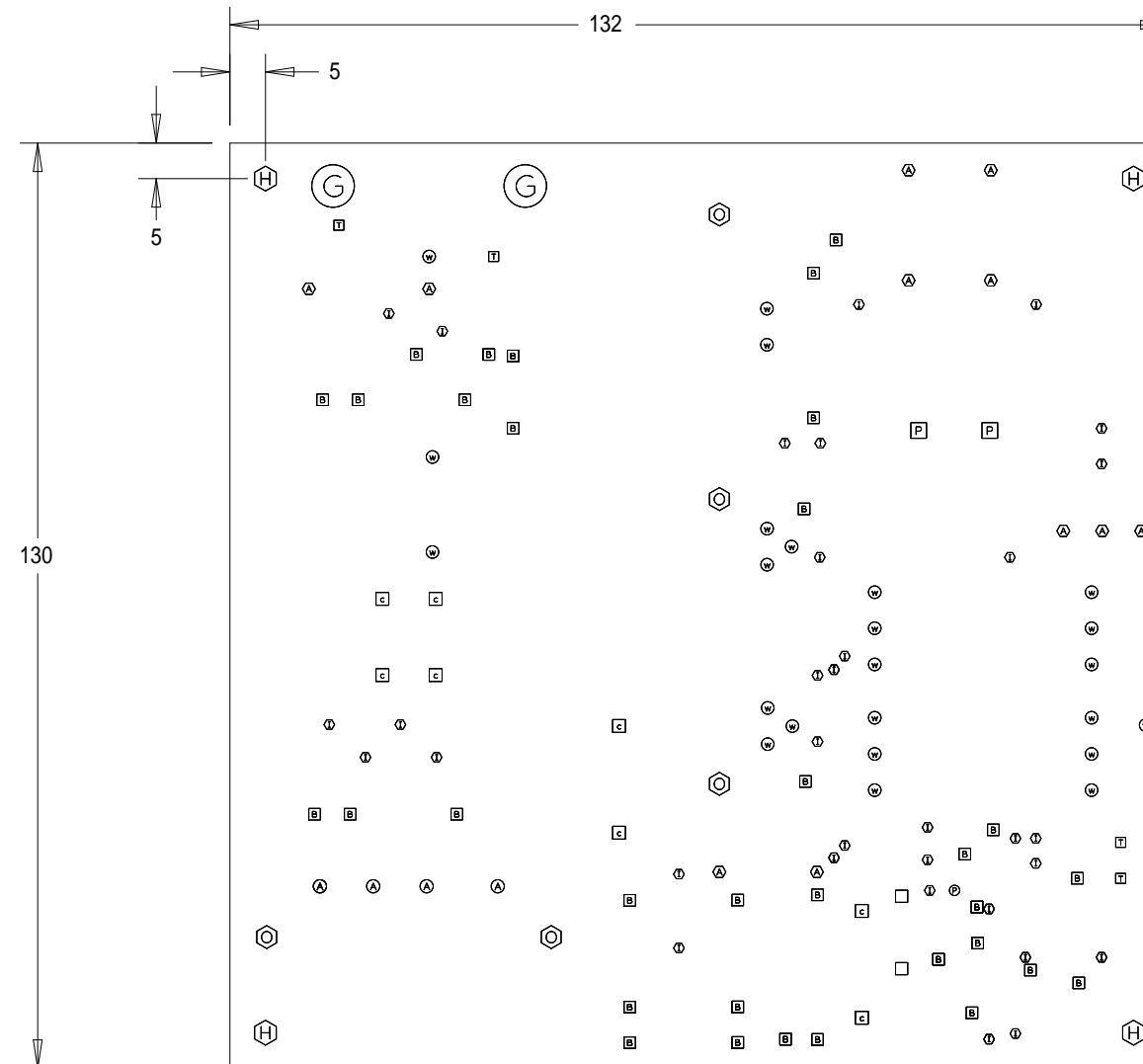




COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	SF /1LAYER		
MINIMAL GAP		300um /11.8mils	
MINIMAL SLIVER		300um /11.8mils	
COPPER THICKNESS		70um(2oz)	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN BOT	
SILKSCREEN	WHITE TOP&BOT		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
	0.8	PLATED	1
	0.8	PLATED	36
	1.0	PLATED	33
	1.1	PLATED	2
	1.2	PLATED	8
	1.4	PLATED	4
	1.6	PLATED	24
	1.8	PLATED	11
	1.9	PLATED	4
	2.2	PLATED	2
	3.2	PLATED	5
	3.5	PLATED	4
	6.0	NON-PLATED	2



C B A			W36/2019 W46/2018 W20/2018
	indice	Description	Date
Contrôle par :		Autorise par:	
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE	
		Subc. 	Dessine: e B Echelle: 1/1
Board: NCP1618 C TLS			
CE DOCUMENT EST LA PROPRIETE DE ON semiconductor IL NE PEUT ETRE UTILISER, REPRODUIT OU COMMUNIQUER SANS SONT AUTHORISATION			Pages: 1/3
THIS DOCUMENT IS ON semiconductor PROPERTY, IT MAY NOT BE USED, REPRODUCED OR TRANSMITTED WITHOUT THEIR APPROVAL.			Format: A3